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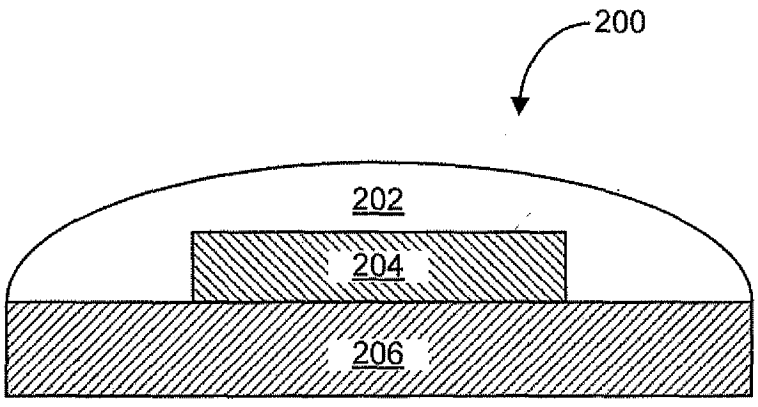
(54) **Hermetic sealing using tin-containing inorganic material with low sintering temperature**

(57) A method for inhibiting oxygen and moisture degradation of a device (e.g., an OLED device) and the resulting device are described herein. To inhibit the oxygen and moisture degradation of the device, a Sn^{2+}-containing inorganic material is used to form a barrier layer on the device. The Sn^{2+}-containing inorganic material can be, for example, SnO, blended SnO & P_2O_5 powders, and blended SnO & BPO_4 powders.

FIG.2



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EUROPEAN SEARCH REPORT

Application Number
EP 08 15 1843

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The present search report has been drawn up for all claims

Place of search	Date of completion of the search	Examiner
The Hague	28 May 2009	Bakos, Tamás

CATEGORY OF CITED DOCUMENTS

X : particularly relevant if taken alone
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For more details about this annex : see Official Journal of the European Patent Office, No. 12/82

专利名称(译)	使用低烧结温度的含锡无机材料进行气密密封		
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其他公开文献	EP1965453A2		
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摘要(译)

本文描述了用于抑制装置（例如，OLED装置）的氧气和水分降解的方法以及所得装置。为了抑制器件的氧和水分降解，使用含Sn 2+的无机材料在器件上形成阻挡层。含Sn 2+的无机材料可以是例如SnO，混合的SnO和P 2 O 5粉末，以及混合的SnO和BPO 4粉末。